

New SRF Facility at CERN

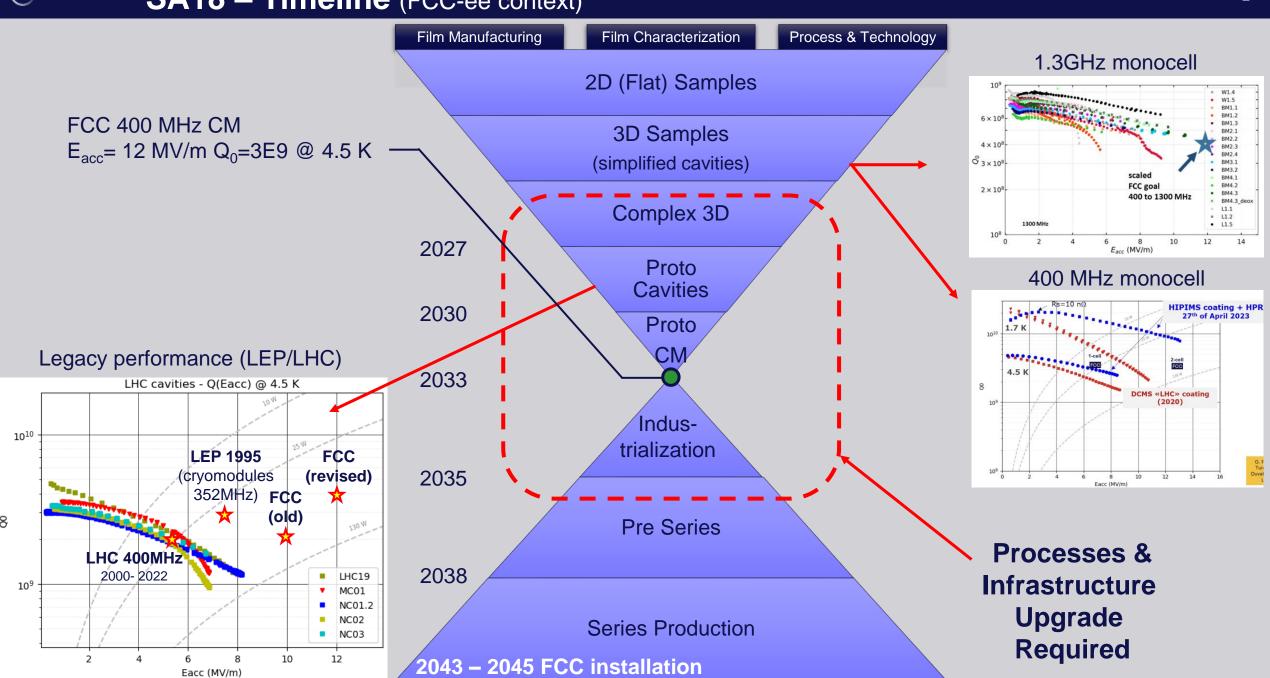
SA18

D. Smekens

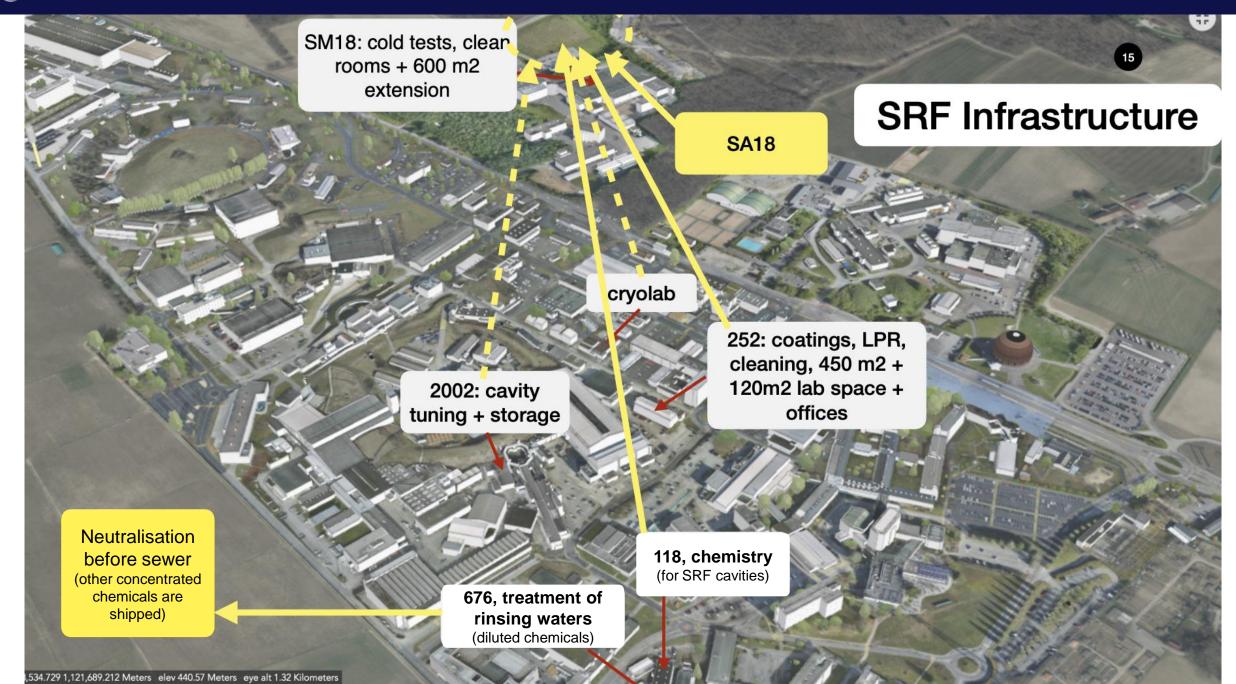
FCC Week 2023, London

Technology R&D: SRF Technology (II), Thursday 8th June

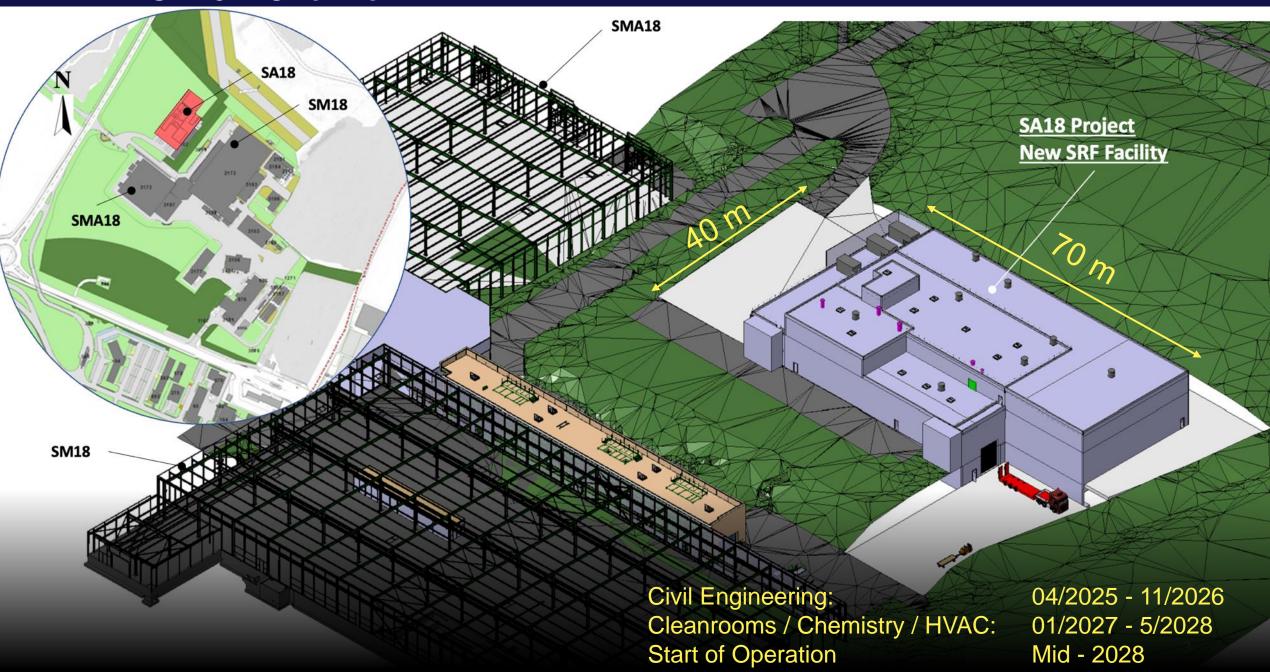
SA18 – Timeline (FCC-ee context)



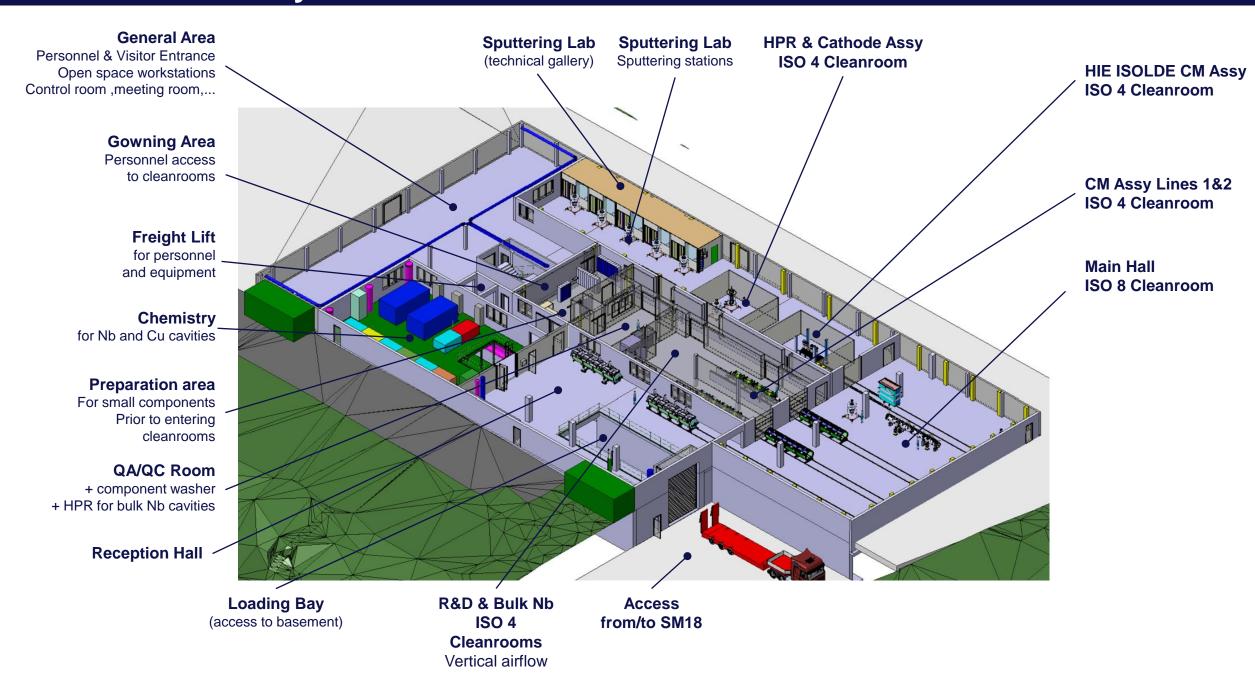






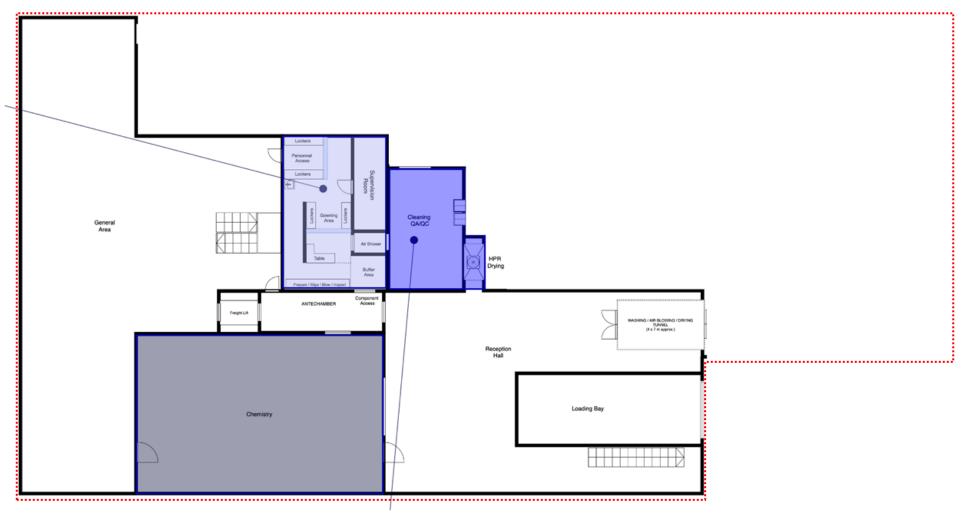


SA18 – Layout



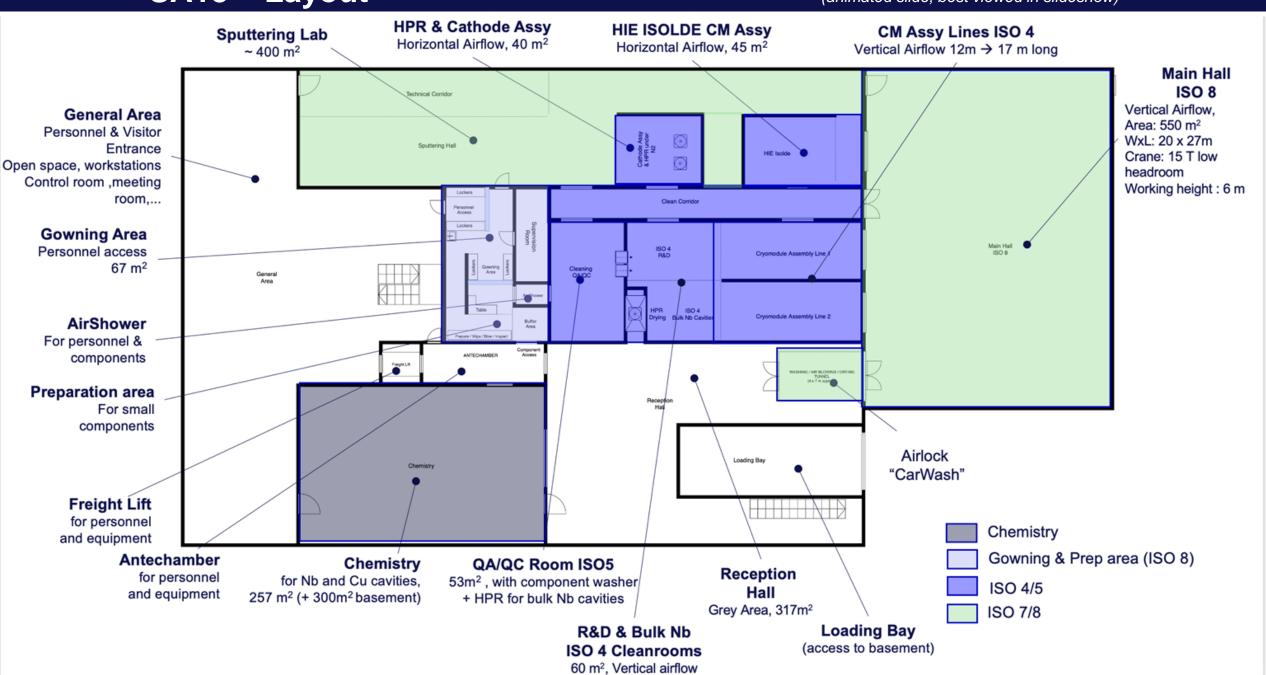
Gowning Area Supervision Room

Air Shower Preparation / Transit Area



QA/QC Room

Particle Counting
Component washer
+ HPR for bulk Nb cavities





SA18 – Chemistry

Surface Etching Chemistry for Copper & Niobium

260 m² chemistry lab, over 2 floors.

Infrastructure designed specifically for chemistry of SRF cavities

Better control of environment, air T + RH

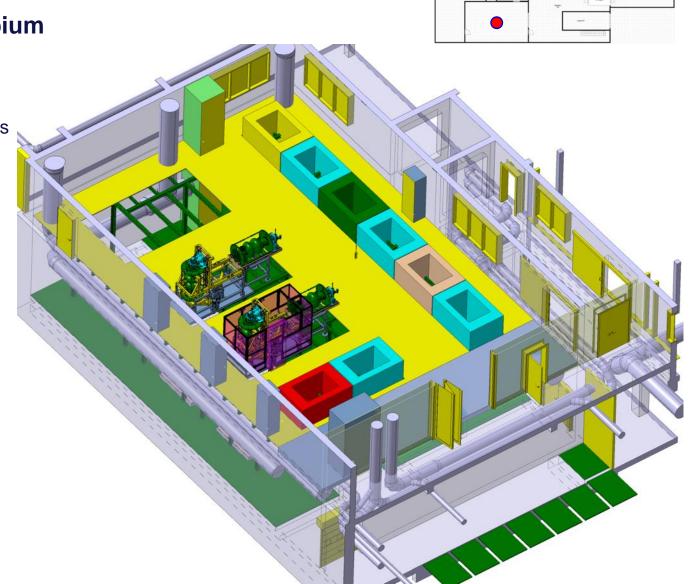
Increased working height for multi-cell cavities

Minimum delay chemistry → sputtering

Direct access to cleanrooms

Equipped with:

- EP chemical skids for Copper and Niobium, designed to leave minimum residuals in cavities
- EP to replace SUBU for copper etching
- Waste (rinsing) water treatment in situ: neutralisation + evaporator





SA18 – Chemistry

Surface Etching Chemistry for Copper & Niobium

IMMERSION BATHS

- Final Degreasing
- Final Rinsing
- Stripping
- Rinsing after Passivation
- Passivation

Cu EP by CIRCULATION

 Electropolishing setup for Cu Cavities (tanks and circulation skid underneath at basement level)

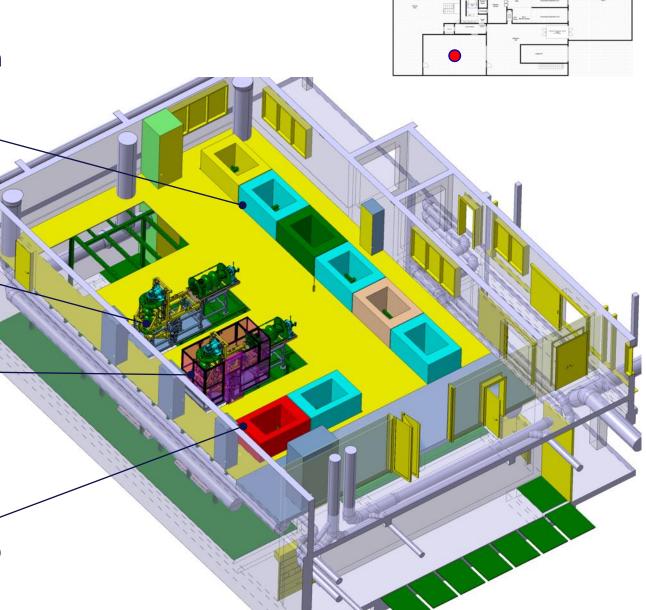
Nb EP by CIRCULATION

- Electropolishing setup for Nb Cavities (tanks and circulation skid underneath at basement level)
- · BCP process also possible

IMMERSION Cu EP

(for RF open structures e.g. SWELL)

- · Copper Electropolishing bath
- · Rinsing bath





SA18 – Sputtering Hall

Tall Hall for the cathode systems to coat large multi-cell cavities

400 m² clean ISO 8 Hall

Tall enough for multi-cell 400MHz cavities and their cathode system High throughput possible (up to 6 sputtering stations in parallel) Equipped with:

- ISO 4 baldachin for HPR of substrate and of coated cavities
- HPR system operating under inert atmosphere for copper substrate
- clean vacuum furnace for R&D (1.3 GHz cavity size)
- HiPIMS systems with split sputtering system ("dirty" systems inside technical gallery, only cavity bench inside ISO 8)





SA18 – Main Hall (ISO 8)

Clean Assembly Hall for cryomodules

540 m² area (20m x 27 m) for clean mechanical assemblies

ISO 8 cleanroom with air T + RH control

Equipped with a 14m-span 15 Ton cleanroom crane

Working height under crane: 6m

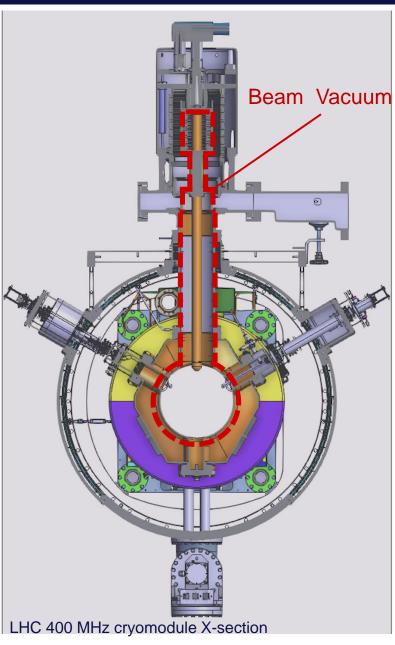
This hall:

- is an airlock at the entrance of the ISO4 rooms to minimize air disturbance and contamination
- Interconnects all ISO 4 cleanrooms:
- Allows for gradual pressurization (+15 Pa) between atm. and ISO 4 rooms (+45Pa)
- is a large clean buffer area to prepare for work in ISO 4
- Could allow to work on up to six 12-metre long cryomodules in parallel











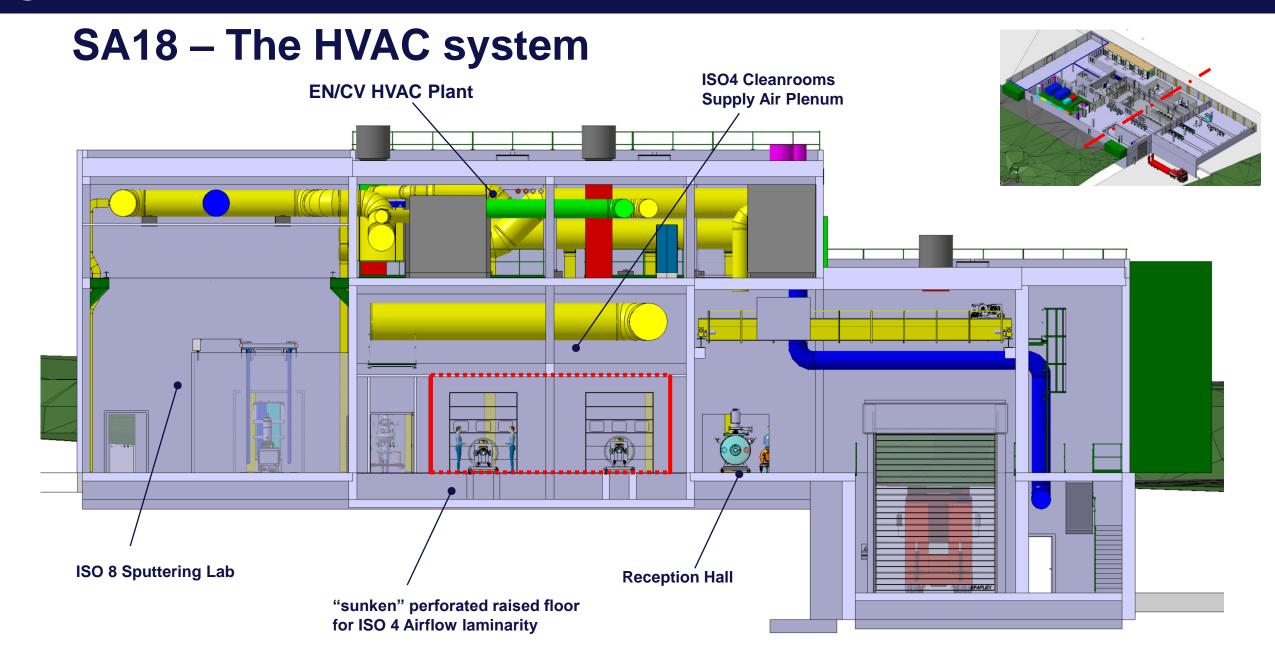
For LEP & LHC, FPCs were installed after cavity train was placed inside the vacuum vessel For FCC, it might also be interesting to have the option to install the FPC after cryostating. **Pros:**

- less limiting for FPC design (FPC+DWT can be much bigger than cryostat enveloppe)
- May allow better location of the ceramic window

Cons:

- Requires to open the cavity after cryostating in clean conditions (ISO 4)
- Requires to keep the cryomodule external surfaces as clean as possible (ISO 8) during assembly







Summary

A clean, customized infrastructure dedicated to SRF, in operation by mid 2028

Allows for a much leaner process with minimum non added-value steps than what is currently possible at CERN.

Highly critical for SRF performance, esp. for complex thin films technology more prone to defects.

For the LHC spares, 75% of cavities needed re-processing. Overall (all cavity types) the failure rate is around 50%.

→ Huge impact on R&D and prototyping due to low throughput overall

Aim: Lower failure rate, down to 20% & increased throughput at equivalent staffing level. Process not limited by infrastructure!

A custom-tailored infrastructure is essential to:

- 1. Achieve no-breach of cleanliness, Air T and RH control, quick clean transit over the entire process
- 2. Reduce risk: less process steps (e.g. transport), more automated steps (e.g. washers), more QC (better defect detection)
- 3. Be adapted to new/enhanced chemistry (new EP, clean substrate HPR,...) and sputtering (HiPIMS, ...) technologies
- 4. Allow to significantly increase throughput, and / or intervene on multiple cryomodules in parallel if required
- 5. Make possible a greener SRF: reduced water consumption, use of sterile air instead of pure nitrogen, use of heat-pumps, ...



Thank you for your attention

Questions?

Acknowledgements

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